





40V P-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

| V _{(BR)DSS} | R _{DS(on)} | I _D T _A = 25°C |
|----------------------|--------------------------------|---|
| -40V | 51mΩ @ V _{GS} = -10V | -10.5A |
| | 85mΩ @ V _{GS} = -4.5V | -8.4A |

Description and Applications

This MOSFET has been designed to minimize the on-state resistance $(R_{DS(on)})$ and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- Backlighting
- DC-DC Converters
- · Power management functions

Features and Benefits

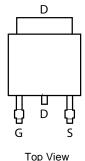
- 100% Unclamped Inductive Switch (UIS) test in production
- Low on-resistance
- Fast switching speed
- "Green" component and RoHS compliant (Note 1)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

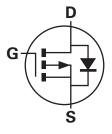
- Case: TO252
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0 (Note 1)
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish annealed over Copper leadframe.
 Solderable per MIL-STD-202, Method 208
- · Weight: 0.33 grams (approximate)



Top View



Pin-Out



Equivalent Circuit

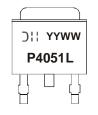
Ordering Information (Notes 1 & 2)

| Product | Grade | Marking | Reel size (inches) | Tape width (mm) | Quantity per reel |
|----------------|------------|---------|--------------------|-----------------|-------------------|
| DMP4051LK3-13 | Commercial | P4051L | 13 | 16 | 2,500 |
| DMP4051LK3Q-13 | Automotive | P4051L | 13 | 16 | 2,500 |

Notes:

- 1. Diodes, Inc. defines "Green" products as those which are RoHS compliant and contain no halogens or antimony compounds; further information about Diodes Inc.'s "Green" Policy can be found on our website. For packaging details, go to our website.
- 2. Products with Q-suffix are automotive grade. Automotive products are electrical and thermal the same as the commercial, except where specified.

Marking Information



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Maximum Ratings $@T_A = 25^{\circ}C$ unless otherwise specified

| Characteristic | | | Symbol | Value | Unit |
|---|----------------|--------------------------------------|-----------------|-------|------|
| Drain-Source voltage | | | V_{DSS} | -40 | V |
| Gate-Source voltage (Note 3) | | V _{GS} | ±20 | V | |
| Single Pulsed Avalanche Energy (Note 9) | | (Note 9) | E _{AS} | 50 | mJ |
| Single Pulsed Avalanche Current (Note 9) | | I _{AS} | 20.3 | А | |
| | | (Note 5) | | -10.5 | |
| Continuous Drain current | $V_{GS} = 10V$ | $T_A = 70^{\circ}C \text{ (Note 5)}$ | I_{D} | -8.40 | Α |
| | | (Note 4) | | -7.2 | |
| Pulsed Drain current | $V_{GS} = 10V$ | (Note 6) | I _{DM} | -28.9 | Α |
| Continuous Source current (Body diode) (Note 5) | | I _S | -10.1 | Α | |
| Pulsed Source current (Body diode) (Note 5) | | I _{SM} | -28.9 | A | |

Thermal Characteristics @TA = 25°C unless otherwise specified

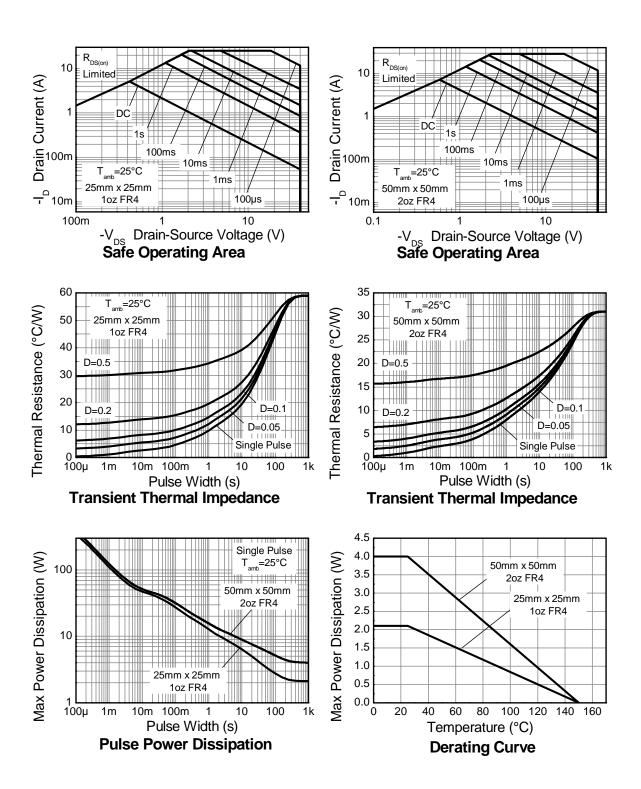
| Characteristic | | Symbol | Value | Unit | |
|---|----------|-----------------------------------|--------------|------------|--|
| | (Note 4) | | 4.18 33.4 | | |
| Power dissipation Linear derating factor | (Note 5) | P _D | 8.9 71.4 | W mW/°C | |
| | (Note 7) | | 2.14 17.1 | | |
| | (Note 4) | | 29.9 | | |
| Thermal Resistance, Junction to Ambient | (Note 5) | $R_{	hetaJA}$ | 14.0 | 2011 | |
| | (Note 7) | Ť | 58.4 | °C/W | |
| Thermal Resistance, Junction to Lead | (Note 8) | $R_{	heta JL}$ | 2.46 | | |
| Operating and storage temperature range | • | T _J , T _{STG} | -55 to 150 | °C | |

Notes:

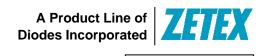
- 3. AEC-Q101 V_{GS} maximum is ±16V.
- 4. For a device surface mounted on 50mm x 50mm x 1.6mm FR4 PCB with high coverage of single sided 2oz copper, in still air conditions; the device is measured when operating in a steady-state condition.
- 5. Same as note 4, except the device is measured at t ≤ 10 sec.
 6. Same as note 4, except the device is pulsed with D = 0.02 and pulse width 300µs. The pulse current is limited by the maximum junction temperature.
- 7. For a device surface mounted on 25mm x 25mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.
- 8. Thermal resistance from junction to solder-point (at the end of the drain lead).
 9. UIS in production with L = 100μH, V_{DD} = -40V.



Thermal Characteristics







Electrical Characteristics @TA = 25°C unless otherwise specified

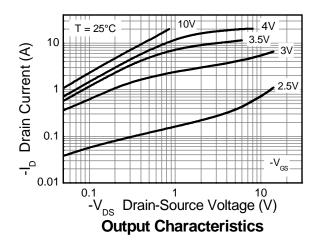
| Characteristic | Symbol | Min | Тур | Max | Unit | Test Co | ndition |
|---|----------------------|------|-------|-------|------|--|-------------------|
| OFF CHARACTERISTICS | | | | | | | |
| Drain-Source Breakdown Voltage | BV _{DSS} | -40 | _ | _ | V | $I_D = -250 \mu A, V_{GS}$ | = 0V |
| Zero Gate Voltage Drain Current | I _{DSS} | _ | _ | -0.5 | μΑ | $V_{DS} = -40V, V_{GS}$ | = 0V |
| Gate-Source Leakage | I _{GSS} | _ | _ | ±100 | nA | $V_{GS} = \pm 20V, V_{DS}$ | = 0V |
| ON CHARACTERISTICS | | | | | | | |
| Gate Threshold Voltage | V _{GS(th)} | -1.0 | | -3.0 | V | $I_D = -250 \mu A, V_{DS}$ | = V _{GS} |
| Static Drain Source On Decistones (Note 10) | | | 0.041 | 0.051 | Ω | $V_{GS} = -10V, I_{D} = -$ | -12A |
| Static Drain-Source On-Resistance (Note 10) | R _{DS (ON)} | _ | 0.059 | 0.085 | 12 | $V_{GS} = -4.5V, I_{D} =$ | -8A |
| Forward Transconductance (Notes 10 & 11) | 9fs | _ | 16.6 | _ | S | $V_{DS} = -15V, I_{D} = -15V$ | -12A |
| Diode Forward Voltage (Note 10) | V_{SD} | _ | -0.98 | -1.2 | V | $I_S = -12A, V_{GS} = 0$ | VO |
| Reverse recovery time (Note 11) | t _{rr} | | 138 | _ | ns | I _S = -12A, di/dt = 100A/μs | |
| Reverse recovery charge (Note 11) | Qrr | _ | 841 | _ | nC | | |
| DYNAMIC CHARACTERISTICS (Note 11) | | | | | | | |
| Input Capacitance | Ciss | _ | 674 | _ | pF | ., | 0) / |
| Output Capacitance | Coss | _ | 115 | _ | pF | $V_{DS} = -20V, V_{GS} = -100$ | = UV |
| Reverse Transfer Capacitance | C_{rss} | _ | 67.7 | _ | pF | 71 = 1101112 | |
| Total Gate Charge (Note 12) | Q_g | _ | 7.0 | _ | nC | $V_{GS} = -4.5V$ | |
| Total Gate Charge (Note 12) | Q_g | _ | 14 | _ | nC | $V_{DS} = -20V$ $I_{D} = -12A$ | |
| Gate-Source Charge (Note 12) | Qgs | _ | 2.2 | _ | nC | | |
| Gate-Drain Charge (Note 12) | Q_{gd} | _ | 3.7 | _ | nC | | |
| Turn-On Delay Time (Note 12) | t _{D(on)} | _ | 2.3 | _ | ns | $V_{DD} = -20V, V_{GS} = -10V$ $I_{D} = -12A, R_{G} \cong 6.0\Omega$ | |
| Turn-On Rise Time (Note 12) | t _r | _ | 14.1 | _ | ns | | |
| Turn-Off Delay Time (Note 12) | t _{D(off)} | _ | 25.1 | _ | ns | | |
| Turn-Off Fall Time (Note 12) | t _f | _ | 14.3 | _ | ns | | |

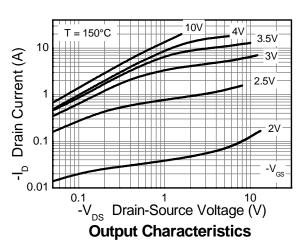
Notes:

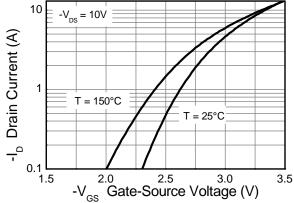
- 10. Measured under pulsed conditions. Pulse width $\leq 300 \mu s;$ duty cycle $\leq 2\%$
- 11. For design aid only, not subject to production testing.12. Switching characteristics are independent of operating junction temperatures.

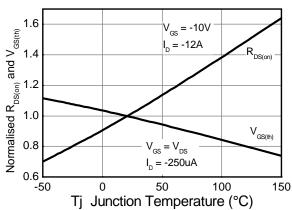


Typical Characteristics



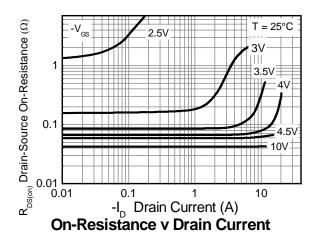


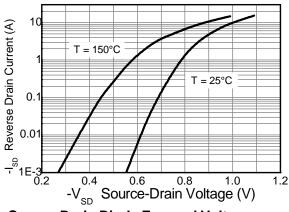




Typical Transfer Characteristics



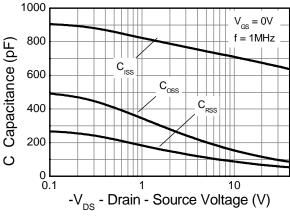


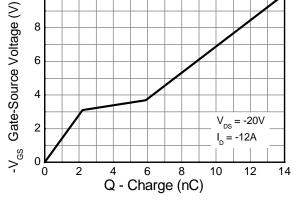


Source-Drain Diode Forward Voltage



Typical Characteristics - continued

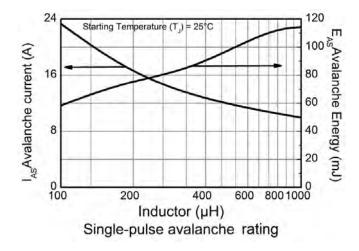




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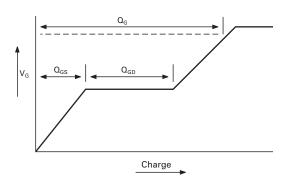
Capacitance v Drain-Source Voltage

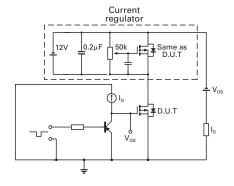
Gate-Source Voltage v Gate Charge





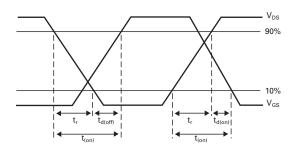
Test Circuits

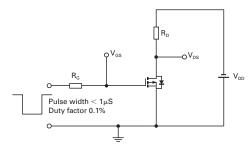




Basic gate charge waveform

Gate charge test circuit





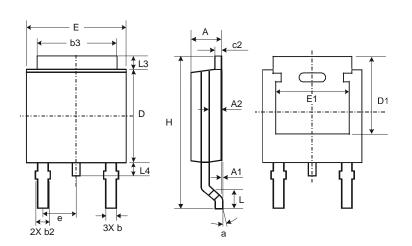
Switching time waveforms

Switching time test circuit



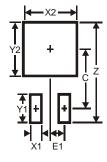


Package Outline Dimensions



| TO252 | | | | | |
|----------------------|------|-------|-------|--|--|
| Dim | Min | Max | Тур | | |
| Α | 2.19 | 2.39 | 2.29 | | |
| A1 | 0.00 | 0.13 | 0.08 | | |
| A2 | 0.97 | 1.17 | 1.07 | | |
| þ | 0.64 | 0.88 | 0.783 | | |
| b2 | 0.76 | 1.14 | 0.95 | | |
| b3 | 5.21 | 5.46 | 5.33 | | |
| c2 | 0.45 | 0.58 | 0.531 | | |
| D | 6.00 | 6.20 | 6.10 | | |
| D1 | 5.21 | _ | _ | | |
| е | _ | _ | 2.286 | | |
| Е | 6.45 | 6.70 | 6.58 | | |
| E1 | 4.32 | _ | _ | | |
| Н | 9.40 | 10.41 | 9.91 | | |
| L | 1.40 | 1.78 | 1.59 | | |
| L3 | 0.88 | 1.27 | 1.08 | | |
| L4 | 0.64 | 1.02 | 0.83 | | |
| а | 0° | 10° | _ | | |
| All Dimensions in mm | | | | | |

Suggested Pad Layout



| Dimensions | Value (in mm) |
|------------|---------------|
| Z | 11.6 |
| X1 | 1.5 |
| X2 | 7.0 |
| Y1 | 2.5 |
| Y2 | 7.0 |
| С | 6.9 |
| E1 | 2.3 |





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